

Nidec-Read to Exhibit Products at Semicon Japan 2015

09/12/2015

We are pleased to inform that we will be participating at Semicon Japan 2015, held in Tokyo, 16th-18th December 2015. On this occasion, NIDEC-READ will exhibit the world's finest diameter "MEMS spring probe" applicable for probe tests requiring 60µm bump pitch and its manufacturing process line. If you are looking for AOI equipment, we are glad to provide our best test solutions for you. Our flagship model, "RWi-series" which is available for 2D/3D & High-Speed Scanning is also introduced. Additionally, our newly introduced "IoT solutions" will appear at the site. We are looking forward to seeing you.

■ Product Lineup

- Optical wafer bump inspection system "RWi-300"
- MEMS spring probe/ process line
- IoT solution "IDEAS" etc.

■ Information

- Period : From December 16 (Wed) to 18 (Fri), 2015
- Venue : Tokyo Big Sight
- Booth : 1708
- Official site : <http://www.semiconjapan.org/en/exhibits>